

The effect of strong and weak interfaces on thermophysical properties of metal matrix composites reinforced with high modulus and high thermal conductivity C fibres – K 1100

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Coefficient of thermal expansion [x10⁻⁶K⁻¹]



Thornel K1100 carbon fibre





Tensile strength [GPa]	3.10
Tensile modulus [GPa]	965
Density [kg/m ³]	2200
Filament diameter [µm]	10
Carbon Assay [%]	99+
Surface Area [m ² /kg]	400
Electrical Resistivity [μΩ.m]	1.1 – 1.3
TC in longitudinal direction [W m ⁻¹ K ⁻¹]	900 - 1000
TC in transversal direction [W m ⁻¹ K ⁻¹]	2.4
Longitudinal CTE at 21°C [10 ⁻⁶ K ⁻¹]	- 1.5
Transversal CTE at 21°C [10 ⁻⁶ K ⁻¹]	12.0



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Cu-C composite – - no wetting

- no reaction



Mg-C composite – no wetting - no reaction with



allov	carbide	temperature	contact angle		
		[°C]	[°]		
Cu	Cr ₃ C ₂	1100	47		
Cu	Cr ₃ C ₂	1150	44		
Cu	TiC	1100-1200	112-109		
Cu	ZrC	1100	135		

For both systems the improvement of interfacial bonding is a necessity

in Cu-C composite by alloying with Cr in Mg-C composite by alloying with Al



AI-C composite strong interfacial reaction that needs to be avoided





Alloying of AI with surface active element Mg was adopted





Infiltration parameters	Cu-C	AI-C	Mg-C
Temperature [℃]	1200	750	730
Time [s]	300	120	300
Pressure [MPa]	6	5	8





Structure of Cu0.2Cr-K1100 composite

Structure of Cu1Cr-K1100 composite



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Structure of AI3Mg-K1100 composite a) without and b) with TiN separator particles





Structure of Mg2Al-K1100 composite



















Cu-K1100

Cu0.2Cr-K1100

Cu1Cr-K1100



Al3Mg-K1100

Al3Mg-K1100 s TiN

Mg2Al-K1100







Cu0.2Cr-K1100

Cu1Cr-K1100

Al3Mg-K1100

Mg2Al-K1100



℃000



℃000



℃000



350℃ Al3Mg-K1100 s TiN



350℃













- > negative CTE in the whole temperature range
- small differences in thermal expansion
- Stronger interfaces in v Al3Mg-C and Mg2Al-C composites
- smaller residual stresses in Al3Mg-C and Mg2Al-C composites

CTE [10 ⁻⁶ K ⁻¹]	Cu-K1100		Cu1Cı	Cr-K1100 Al3Mg-K1		g-K1100	Al3Mg-K1100 s TiN		Mg2Al-K1100	
150-250℃	heat.	cool.	heat.	cool.	heat.	cool.	heat.	cool.	heat.	cool.
	-0.7	-0.7	-0.9	-0.9	-1.9	-1.7	-1.8	-1.6	-1.1	-0.9
CTE _τ	21.1	19.7	21.4	20.6	23.8	20.8	27.4	25.3	26.4	23.2



Conclusions

- the interfacial bonding in metal matrix (Cu, Al, Mg) can be effectively influenced by proper matrix alloying and kinetic parameters of infiltration
- higher TC and lower CTE in all composites has been achieved when compared with pure Cu
- composites can be used as heat sink materials particularly in those cases where materials with high thermal conductivity and low CTE are required and the anisotropy can be accepted (utilized)
- MgAI-K1100 and AIMg-K1100 can be used in applications where low density is required
- ❑ the role of interface in the composites reinforced with unidirectionally aligned continuous fibres appears to be not as dominant as in short fibre or particulate reinforced composites



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